



FABRICATION (L24)
SILKSCREEN TOP (L26)
ROUTING TOP (L1) 85x115MM

TMC6130-EVAL_V2.1 01.12.2014

Top Side		
Layers	Final Thickness	
COMP Cu	0.070mm	Top Layer 1
Prepreg	0.180mm	
Cu	0.070mm	GND-Plane Layer 2
Innerlayer	1.080mm	
Cu	0.070mm	POWER-Plane Layer 3
Prepreg	0.180mm	
SOLDER Cu	0.070mm	Bottom Layer 4

Bottom Side

1.72 mm +/- 0.1

NOTICE: CONFIDENTIAL MATERIAL
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written permission of Trinamic.

NOTES : (UNLESS SPECIFIED OTHERWISE)

- 1) MATERIAL : FR-4- 2 NATURAL EPOXY/FIBERGLASS
- 2) APPLY SOLDERMASK ON BOTH SIDES
COLOR : WHITE
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO SOLDERMASK PHOTO PLOT FILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
- 3) FINISH ALL EXPOSED COPPER SURFACES WITH IMMERSION GOLD.
- 4) HOLE SIZES APPLY AFTER PLATING.
- 5) APPLY SILKSCREEN TO BOTH SIDE
COLOR : BLACK
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PHOTO PLOT FILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
- 6) MODIFIED PHOTO PLOT FILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
- 7) ALL PRINTED CIRCUIT BOARD NETS SHALL BE ELECTRICALLY TESTED FOR OPENS AND SHORTS.
- 8) FABRICATION OF PCB TO COMPLY WITH IPC-A-600 CLASS II , CURRENT REVISION.

APPROVALS		DATE	TRINAMIC			
DRAWN: Elli Puusepp		01.12.2014	TMC6130-EVAL V2.1 Assembly Drawing Top			
CHECKED: Mart Liik		01.12.2014				
PROJ MGR: Kaido Kevvai		01.12.2014				
CLIENT:		SIZE C	DRAWING NO: 8707005921	SCALE 1 : 1	SHEET 1 OF 1	REVISION V2.1